

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously presented) A method of communicating semiconductor manufacturing information, the method comprising:

 providing, by a first service provider, a lot of semiconductor components to a second service provider for processing;

 receiving, by the first service provider, first information associated with the processing, from the second service provider;

 generating, by the first service provider, second information responsive to the first information; and

 outputting, by the first service provider, the second information to a customer affiliated with the second service provider.

2. (Original) The method of claim 1 further comprising:

 in association with providing the lot of semiconductor components to the second service provider for processing, providing, by the first service provider, a virtual work order to the second service provider.

3. (Original) The method of claim 1, wherein the first service provider and the second service provider are separate business organizations.

4. (Original) The method of claim 1, wherein the first service provider includes a first manufacturing execution system (“MES”), the second provider includes a second MES, the first MES and the second MES are dissimilar.

5. (Original) The method of claim 1, wherein the first information includes work-in-process (“WIP”) information.

6. (Previously presented) A method of communicating semiconductor manufacturing information, the method comprising:

providing, by a first service provider, a lot of semiconductor components to a second service provider for processing;

receiving, by the first service provider, first information associated with the processing, from the second service provider

generating, by the first service provider, second information responsive to the first information; and

outputting, by the first service provider, the second information to a customer affiliated with the second service provider;

wherein the first information includes work-in-process (“WIP”) information, wherein the second information includes a determination of whether a time duration associated with the processing of a component of the lot exceeds a predetermined duration of time.

7. (Original) The method of claim 5, wherein receiving the WIP information is by periodically receiving the WIP information, in response to passage of a predetermined period of time.

8. (Original) The method of claim 1, wherein the first information includes shipping information.

9. (Original) The method of claim 1, wherein the first information includes lot yield information.

10. (Original) The method of claim 1, wherein receiving the first information and outputting the second information are by receiving and outputting through a network.

11. (Original) The method of claim 10, wherein the network is a global computer network.

12. (Original) The method of claim 10, wherein receiving the first information and outputting the second information are by receiving and outputting using the file transfer protocol (“FTP”).

13. (Original) The method of claim 10, wherein receiving the first information and outputting the second information are by receiving and outputting using the hyper text transfer protocol (“HTTP”).

14. (Original) The method of claim 1, wherein the lot of semi-conductor components is a lot of integrated chips (“IC’s”).

15. (Original) The method of claim 1, wherein the second information includes the first information.

16. (Previously presented) A system for communicating semiconductor manufacturing information, comprising:

an information handling system (“IHS”) associated with a first service provider for:
from a second service provider, receiving first information associated with processing of a lot of semiconductor components, the lot having been provided by the first service provider to the second service provider for the processing;
generating second information responsive to the first information; and
to a customer affiliated with the second service provider, outputting the second information.

17. (Original) The system of claim 16, wherein the first service provider provides a virtual work order to the second service provider in association with providing the lot of semiconductor components to the second service provider.

18. (Original) The system of claim 16, wherein the first service provider and the second service provider are separate business organizations.

19. (Original) The system of claim 16, wherein the first service provider includes a first manufacturing execution system (“MES”), the second service provider includes a second MES, and the first MES and the second MES are dissimilar.

20. (Original) The system of claim 16, wherein the first information includes work-in-process (“WIP”) information.

21. (Original) The system of claim 20, wherein the second information includes a determination of whether a time duration associated with the processing of a component of the lot exceeds a predetermined period of time.

22. (Original) The system of claim 20, wherein the IHS is for receiving the WIP information by receiving the WIP information periodically, in response to passage of a predetermined period of time.

23. (Original) The system of claim 16, wherein the first information includes shipping information.

24. (Original) The system of claim 16, wherein the first information includes yield information.

25. (Original) The system of claim 16, wherein the IHS is for receiving the first information and outputting the second information by receiving and outputting through a network.

26. (Original) The system of claim 25, wherein the network is a global computer network.

27. (Original) The system of claim 25, wherein the IHS is for receiving the first information and outputting the second information by receiving and outputting using the file transfer protocol (“FTP”).

28. (Original) The system of claim 25, wherein the IHS is for receiving the first information and outputting the second information by receiving and outputting using the hyper text transfer protocol (“HTTP”).

29. (Original) The system of claim 16, wherein the lot of semiconductor components is a lot of integrated chips (“IC’s”).

30. (Original) The system of claim 16, wherein the second information includes the first information.